Materials Declaration Form

IPC	**1752**	**Version**	**2**
Form Type *	Distribute		
Sectionals *	Material Info Manufacturing Info	**Subsectionals ***	A-D *** : Required Field**

Supplier Information			
Company Name *	STMicroelectronics	**Response Date ***	2014-09-26
Contact Name *	Refer to " Supplier Comment" section	**Contact Title**	Refer to " Supplier Comment" section
Contact Phone *	Refer to " Supplier Comment" section	**Contact Email ***	Refer to " Supplier Comment" section
Authorized Representative *	Giovanni Giacopello	**Representative Title**	AMS & IPD Materials Declaration Champion
Representative Phone *	Refer to " Supplier Comment" section	**Representative Email ***	Refer to " Supplier Comment" section
Supplier Comment	Online Technical Support - STMicroelectronics : http://www.st.com/internet/com/support/online_tech_support.jsp		

Uncertainty Statement

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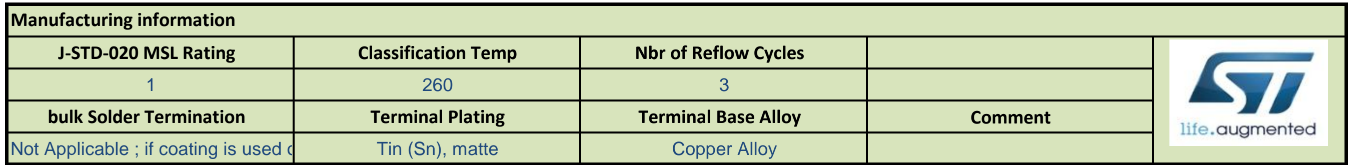
Legal Statement

Supplier Acceptance *	true	**Legal Declaration ***	Standard

Legal Statement

Supplier certifies that it gathered the provided information and such information is true and correct to the best of its knowledge and belief, as of the date that Supplier completes this form. Supplier acknowledges that Company will rely on this certification in determining the compliance of its products. Company acknowledges that Supplier may have relied on information provided by others in completing this form, and that Supplier may not have independently verified such information. However, in situations where Supplier has not independently verified information provided by others, Supplier agrees that, at a minimum, its suppliers have provided certifications regarding their contributions to the part(s), and those certifications are at least as omprehensive as the certification in this paragraph. If the Company and the Supplier enter into a written agreement with respect to the identified part(s), the terms and conditions of that agreement, including any warranty rights and/or remedies provided as part of that agreement, will be the sole and exclusive source of the Supplier’s liability and the Company’s remedies for issues that arise regarding information the Supplier provides in this form.

Product				
Mfr Item Number	**Mfr Item Name**	**Version**	**Mfr Site**	**Date**
	C1O7*6B34B6F	A	Z8GA	2014-09-26
	Amount	**UoM**	**Unit type**	**ST ECOPACK Grade**
	80.00	mg	Each	ECOPACK® 2



Manufacturing information				
J-STD-020 MSL Rating	**Classification Temp**	**Nbr of Reflow Cycles**		
1	260	3		
bulk Solder Termination	**Terminal Plating**	**Terminal Base Alloy**	**Comment**	
Not Applicable ; if coating is used c	Tin (Sn), matte	Copper Alloy		

Package Designator	**Size**	**Nbr of instances**	**Shape**	
DSO	4.85X3.9X1.52	8	gull wing	
Comment	Package:SO 08 .15 JEDEC; MDF valid for STS10P3LLH6			

QueryList : ROHS directive 2011/65/EU _ July 2011	
Query	**Response**
Product(s) meets EU RoHS requirement without any exemptions	**true**
Product(s) meets EU RoHS requirements except lead in solder and this usage may qualify under the lead in solder '7b' exemption (other selected exemptions may apply)	false
Product(s) meets EU RoHS requirements by application of the selected exemption(s)	false
Product(s) does not meet EU RoHS requirements and is not under exemptions	false
Product(s) is obsolete, no information is available	false
Product(s) is unknown, no information is available	false

Exemption Id.	**Description**

QueryList : REACH-17th December 2014				
Query				**Response**
The product does not contain REACH Substances Of Very High Concern above the limits per the definition within REACH				**true**
CategoryLevel_Name	CategoryLevel_Threshold	amount in product (mg)	Application	ppm in product

Material Composition Declaration						Mfr Item Name	C1O7*6B34B6F					
Homogeneous Material	Material Group	Mass	UoM	Level	Substance Category	Substance	CAS	Exempt	Mass	UoM	Concentration in homogeneous material (ppm)	Concentration in product (ppm)
Silicon die	Other inorganic materials	2.756	mg	supplier	die	Silicon (Si)	7440-21-3		2.656	mg	963716	33200
Silicon die				supplier	metallization	Titanium (Ti)	7440-32-6		0.009	mg	3266	113
Silicon die				supplier	metallization	Tungsten (W)	7440-33-7		0.001	mg	363	13
Die Attach				supplier	passivation	Silicon Nitride (SiN)	12033-89-5		0.001	mg	363	13
Die Attach				supplier	passivation	Silicon Oxide(SiO2)	7631-86-9		0.053	mg	19231	663
Silicon die				supplier	back side metallization	Chromium (Cr)	7440-47-3		0.003	mg	1089	38
Silicon die				supplier	back side metallization	Silver (Ag)	7440-22-4		0.008	mg	2903	100
Silicon die				supplier	back side metallization	Nickel (Ni)	7440-02-0		0.025	mg	9071	313
Leadframe	Copper & its alloys	31.358	mg	supplier	alloy	Copper(CU)	7440-50-8		30.322	mg	966962	379025
Leadframe				supplier	alloy	Iron(Fe)	7439-89-6		0.732	mg	23343	9150
Leadframe				supplier	alloy	Iron Phosphide(FeP)	26508-33-8		0.026	mg	829	325
Leadframe				supplier	alloy	Zinc(Zn)	7440-66-6		0.039	mg	1244	488
Leadframe				supplier	metallization	Silver(Ag)	7440-22-4		0.239	mg	7622	2988
Die attach	Other inorganic materials	0.327	mg	supplier	glue or tape	Silver (Ag)	7440-22-4		0.285	mg	871560	3563
Die attach				supplier	glue or tape	Bismaleimide resin	Proprietary		0.02	mg	61162	250
Die attach				supplier	glue or tape	Isobornyl Methacrylate	7534-94-3		0.02	mg	61162	250
Die attach				supplier	glue or tape	polymer	Proprietary		0.002	mg	6116	25
Bonding wire	Other inorganic materials	0.079	mg	supplier	wire	Copper(CU)	7440-50-8		0.079	mg	1000000	988
encapsulation	Other inorganic materials	41.676	mg	supplier	mold compound	Epoxy Resin	Proprietary		3.127	mg	75031	39088
encapsulation				supplier	mold compound	Phenol Resin	Proprietary		2.085	mg	50029	26063
encapsulation				supplier	mold compound	Silica, vitreous	60676-86-0		36.089	mg	865942	451113
encapsulation				supplier	mold compound	Carbon black	1333-86-4		0.208	mg	4991	2600
encapsulation				supplier	mold compound	Bismuth (Bi)	7440-69-9		0.167	mg	4007	2088
connections coating	Solder	3.804	mg	supplier	solder alloy	Tin (Sn)	7440-31-5		3.804		1000000	47550